

HSM276S

Silicon Schottky Barrier Diode for Balanced Mixer

REJ03G0610-0700

(Previous: ADE-208-039F)

Rev.7.00 Apr 26, 2005

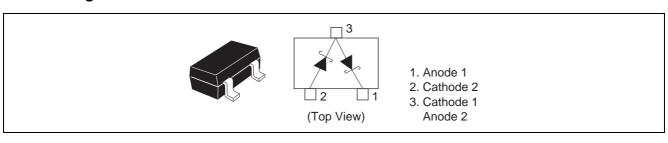
Features

- High forward current, Low capacitance.
- HSM276S which is interconnected in series configuration is designed for balanced mixer use.
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSM276S	C2	MPAK	PLSP0003ZC-A
			(MPAK)

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V_R	3	V
Average rectified current	Io *1	30	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	−55 to +125	°C

Note: 1. Per one device

Electrical Characteristics *1

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse voltage	V_R	3.0	_	_	V	I _R = 1 mA
Reverse current	I _R	_	_	50	μΑ	V _R = 0.5 V
Forward current	I _F	35	_	_	mA	$V_F = 0.5V$
Capacitance	С	_	_	0.90	pF	V _R = 0.5 V, f = 1 MHz
Capacitance deviation	ΔC	_	_	0.10	pF	V _R = 0.5 V, f = 1 MHz
ESD-Capability *2	_	30	_	_	V	C = 200 pF, R = 0 Ω , Both forward and
						reverse direction 1 pulse.

Notes: 1. Per one device

2. Failure criterion ; $I_R \geq 100~\mu A$ at V_R = 0.5 V

Main Characteristic

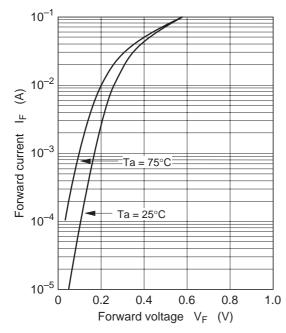


Fig.1 Forward current vs. Forward voltage

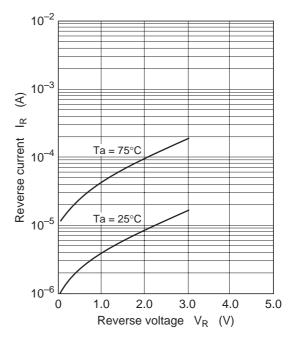
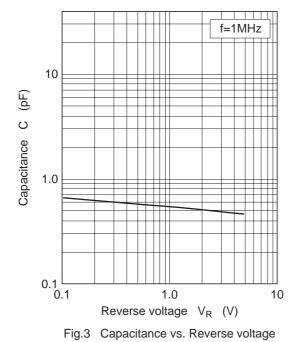
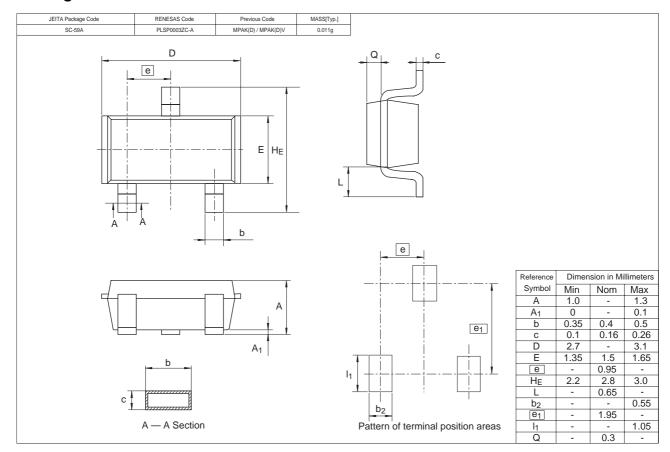


Fig.2 Reverse current vs. Reverse voltage



Package Dimensions



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